

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOSHIHIKO OGURA	12/08/2020
RECEIVING PARTY DATA	
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Property Type	Number
Application Number:	17253115
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DATE SIGNED:	12/17/2020
Total Attachments: 1	
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ASSIGNMENT

Whereas, I/we,
Name

Address

1) **Toshihiko OGURA**

c/o National Institute of Advanced Industrial Science and Technology, Tsukuba Central 1,
1-1, Umezono 1-chome,
Tsukuba-shi, Ibaraki 305-8560 Japan

hereinafter called assignor(s), have invented certain improvements in
IMAGE FORMING METHOD AND IMPEDANCE MICROSCOPE

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless
otherwise indicated below:

filed on December 17, 2020, Serial No. 17/253115; and

Whereas

National Institute of Advanced Industrial Science and Technology
3-1, Kasumigaseki 1-chome,
Chiyoda-ku, Tokyo 100-8921 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States
patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is
hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign,
transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to
this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States
which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of
Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and
assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with
assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal
proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or
desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional,
continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its
successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being
understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and
assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is
executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or
serial number above, and to record this Assignment after such information is added.

INVENTORS

DATE SIGNED

1) :

Toshihiko Ogura

Dec. 8, 2020

Name :

Toshihiko OGURA